

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT7507244

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
RUIPING LI	08/26/2022
JINLONG XU	08/26/2022
BIN LIU	08/26/2022
WEI CHI	08/26/2022
RECEIVING PARTY DATA	
Name:	SHANGHAI XINLONG SEMICONDUCTOR TECHNOLOGY CO., LTD.
Street Address:	BUILDING 18, NO.1888 NEW JINQIAO ROAD
Internal Address:	FREE TRADE ZONE PUDONG
City:	SHANGHAI
State/Country:	CHINA
Postal Code:	201206
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17802712
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	203 659 0388
Email:	ptomail@gziplaw.com
Correspondent Name:	ZIEGLER IP LAW GROUP, LLC.
Address Line 1:	3135 EASTON TURNPIKE
Address Line 2:	SHU I-HUB, W-256
Address Line 4:	FAIRFIELD, CONNECTICUT 06825
ATTORNEY DOCKET NUMBER:	SSIP.7008.USN1
NAME OF SUBMITTER:	DOUGLAS D. ZHANG
SIGNATURE:	/Douglas D. Zhang/
DATE SIGNED:	08/26/2022
This document serves as an Oath/Declaration (37 CFR 1.63).	

Total Attachments: 3

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**COMBINED DECLARATION AND ASSIGNMENT
FOR A UTILITY OR DESIGN PATENT APPLICATION**

As the below named inventor(s), I/we declare that:

1) This declaration and assignment are directed to:

Title of Invention **SHORT-CIRCUIT PROTECTION CIRCUIT, CHIP AND SYSTEM FOR SWITCHED-MODE POWER SUPPLY**

☐ The specification of which is attached hereto; OR

☒ United States application or PCT international application number:

PCT/CN2021/106354 filed on 14 July 2021

☐ As amended on _____ (if applicable);

(I/We hereby authorize and request the Company or its designated attorneys, representatives or agents to insert above the title, application number and filing date of the application, or any other information herein, when known.)

- 2) The above-identified application was made or authorized to be made by me/us.
- 3) I/We believe that I/we are the original and/or joint inventors of a claimed invention in the application.
- 4) I/We hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. §1001 by fine or imprisonment of not more than five (5) years, or both.
- 5) I/We have reviewed and understand the contents of the above-identified application, including the claims, as amended by any amendment referred to above.
- 6) I/We acknowledge the continuing duty to disclose to the United States Patent and Trademark Office all information known to us to be material to patentability of this application, as defined in Title 37, Code of Federal Regulations, Section 1.56, including, for continuation-in-part applications, material information which becomes available between the filing date of the prior application and the filing date of the continuation-in-part application.

Authorization To Permit Access To Application by Participating Office

☒ If checked, the undersigned hereby grants the USPTO authority to provide the European Patent Office (EPO), the Japan Patent Office (JPO), the Korean Intellectual Property Office (KIPO), the World Intellectual Property Office (WIPO), and any other intellectual property offices in which a foreign application claiming priority to the above-identified patent application is filed access to the above-identified patent application. See 37 CFR 1.14(c) and (h). This box should not be checked if the applicant does not wish the EPO, JPO, KIPO, WIPO, or other intellectual property office in which a foreign application claiming priority to the above-identified patent application is filed to have access to the above-identified patent application. In accordance with 37 CFR 1.14(h)(3), access will be provided to a copy of the above-identified patent application with respect to: 1) the above-identified patent application-as-filed; 2) any foreign application to which the above-identified patent application claims priority under 35 U.S.C. 119(a)-(d) if a copy of the foreign application that satisfies the certified copy requirement of 37 CFR 1.55 has been filed in the above-identified patent application; and 3) any U.S. application-as-filed from which benefit is sought in the above-identified patent application. In accordance with 37 CFR 1.14(c), access may be provided to information concerning the date of filing

the Authorization to Permit Access to Application by Participating Offices.

OATH:

I/We do hereby declare that all statements made herein of my/our own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

ASSIGNMENT OF RIGHTS:

Whereas, I/we have invented certain new and useful improvements in the Invention identified above and described in the above-identified patent application(s) and/or patent(s) (hereinafter referred to as "Invention"); and,

Whereas I/we desire to assign my above-identified rights, title and interest in the Invention to the Assignee identified herein;

Now, this indenture witnesseth, that for good and valuable consideration, the receipt whereof is hereby acknowledged, I/we,

Inventor(s) (assignor(s))

<i>Name</i>	<i>Address</i>
Ruiping LI	Building 18, No.1888 New Jinqiao Road Free Trade Zone Pudong Shanghai 201206,China
Jinlong XU	Building 18, No.1888 New Jinqiao Road Free Trade Zone Pudong Shanghai 201206,China
Bin LIU	Building 18, No.1888 New Jinqiao Road Free Trade Zone Pudong Shanghai 201206,China
Wei CHI	Building 18, No.1888 New Jinqiao Road Free Trade Zone Pudong Shanghai 201206,China

do hereby assign, sell and transfer to:

Assignee

<i>Name of Company</i>	<i>Address</i>
SHANGHAI XINLONG SEMICONDUCTOR TECHNOLOGY CO., LTD.	Building 18, No.1888 New Jinqiao Road Free Trade Zone Pudong Shanghai 201206,China

herein referred to as the "Company", its successors and assigns, my entire rights, titles and interests in and to the Invention and improvements made or conceived by me/us described the application(s) listed above and in the following table:

<i>Country</i>	<i>Type of Filing</i>	<i>Application Number</i>	<i>Filing Date</i>	<i>Title</i>
WO	PCT	PCT/CN2021/106354	14 July 2021	SHORT-CIRCUIT PROTECTION CIRCUIT FOR SWITCH POWER SOURCE, AND CHIP AND SYSTEM
CN		CN 202110157438.0	05 February 2021	

(We hereby authorize and request the Company or its delegated attorneys, representatives or agents to insert above the relevant application number, filing date and other information required herein, when known.)

and any and all applications for patent or patents therefrom in any and all countries, including all divisions, continuations, and continuations-in-part, reexaminations, reissues and renewals thereof, and all benefits, rights of priority resulting from the filing of the application(s), and any and all Letters Patent of the United States, and countries foreign thereto, which may be granted or have granted for the Invention, and other benefits accruing or to accrue to us with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, unto the Company;

and I/we hereby authorize and request the Director of the United States Patent and Trademark Office to issue any United States Letters Patent which may issue for the Invention to the Company, as assignee of the whole right, title and interest thereto;

and I/we further agree to, without any further consideration, communicate to the Company or its representatives or nominees any facts known to me/us respecting the Invention and improvements and testify in any legal proceeding, make all rightful oaths, sign and execute all necessary and lawful future documents required or requested for the making and prosecution of any applications of any type for patent, utility model, or other similar rights in all countries including but not limited to, any provisional, non-provisional, continuation, continuation-in-part, divisional, renewal or substitute thereof, for any derivation proceedings relating thereto, and, as to any patents that issue from such applications, for any supplemental examination, derivation proceeding, opposition, post grant review, reissue, re-examination, interpartes review, or extension thereof, and generally do everything possible to aid the Company, its successors, assigns and nominees, to obtain and enforce proper patent protection for the Invention and its improvements in all countries.

Inventor(s) Signature(s)

<i>Name</i>	<i>Signature</i>	<i>Date</i>
Ruiping LI		2022/8/26
Jinlong XU		2022/8/26
Bin LIU		2022/8/26
Wei CHI		2022/8/26